

### FluidJet™ Lift-Off Solution (for MEMs & Compound Semiconductor)

<p><b>FluidJet™</b> <i>Patent Pending Technology for Complete Lift-Off</i></p>	<p><b>Proprietary Tank Design</b> <i>Decreases Defects/Increases Reclaim</i></p>	<p><b>Batch Processing</b> <i>80% Less Solvent, Higher Throughput &amp; Smaller Footprint</i></p>

### Unique Hydraulic, Agitation and Ultrasonic Design

Patent Pending Solvent Based System with *Unique Hydraulic, Agitation and Ultrasonic design* that results in breakthrough MLO performance with higher throughput, significantly reduced chemical use, and less floor space!

#### Reduce Damage

- Improve Lift-Off performance
- No metal redeposition – front and back side
- Fewer suspended particles
- Eliminate feature erosion and scratches

#### 80% Reduction in Chemical Use

- Lower cost of ownership
- Batch immersion eliminates spray control issues

#### Increase Reclaim

- 99% precious metal capture with integrated filters and screens
- Accessible and removable screens provide rapid cleanouts

#### 50% Smaller Footprint

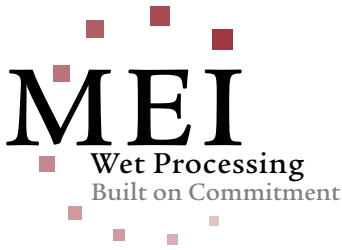
- Efficient fab utilization
- Easy installation and facilities hook up

#### Higher Reliability

- Low PM requirements – no spray nozzle changes
- Reduced scrap
- No complex wafer handling

#### 100 WPH Throughput

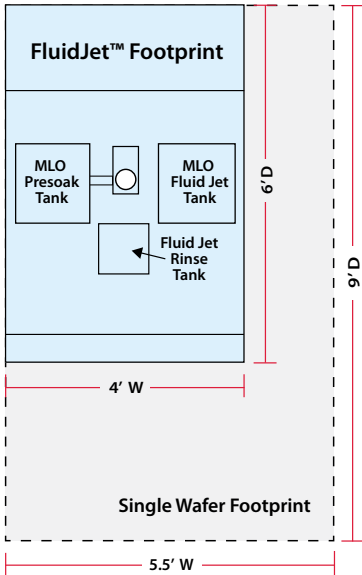
- High uptime
- No daily shutdown for maintenance



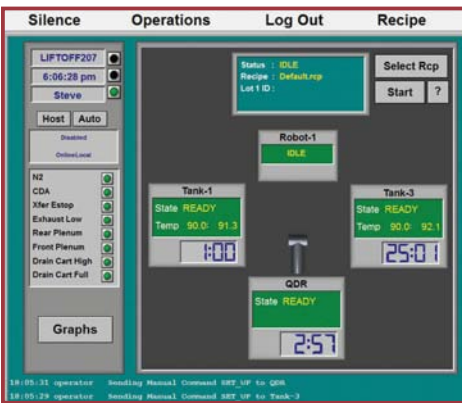
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## FluidJet™

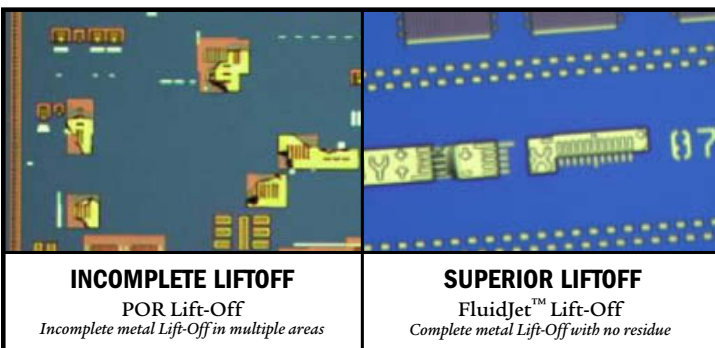
### Small Footprint



FluidJet™ Footprint 50% Smaller than Single Wafer Footprint



Precise Control by IDX Flexware Software



Tested Superior Lift-Off Performance

### MEI Solves Key Issues with Metal Lift-Off

#### Retention

- Challenge of complete metal removal in metal lift-off
- High velocity and agitation required for effective metal stripping

#### Redeposition of Metals in Suspension

- Challenges of tank cleanout and fluid flow to remove metals

#### Throughput

- Multiple single wafer tools required to meet production throughput requirements

#### Costs

- Equipment costs – high cost and low throughput of single wafer machines
- Scrap costs due to complex individual wafer handling
- Downtime and maintenance costs due to PMs and metal contaminants



### Superior Process Control

- SECS/GEM compliant
- Recipe editor
- Advanced process controls
- Unlimited user/permission levels
- Easy-to-use, touch-screen interface
- Error logging and data graphing
- User programmable configuration
- Recipes, speeds, chem control
- Barcode reader compatibility
- Remote access compatible
- I/O monitor displays status

### Analog Control

Analog sensing enables software to control:

- In-tank blending
- Blending ratio creation
- Control DI water inject
- Control temperature
- Recirculation flow
- Spiking volume

### MEI's Award Winning Service and Support

MEI Global Field Service Team

- Final test and verification
- Standard one year parts and labor warranty
- Two year optional warranty
- Full field service support, on-site warranty coverage
- On-site training provided

